

S/N 09/382182

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	HAGIWARA ET AL.	Examiner:	G. GOUDREAU
Serial No.:	09/382182	Group Art Unit:	1763
Filed:	August 24, 1999	Docket No.:	12052.20US01
Title:	METHOD OF FORMING MULTI-LAYER WIRING STRUCTURE.		

CERTIFICATE UNDER 37 CFR 1.6(d):

I hereby certify that this paper is being transmitted by facsimile to the U.S. Patent and Trademark Office on December 6, 2002.

By: Lisa Dorn

Name: Lisa Dorn

AMENDMENT UNDER RULE 111Commissioner for Patents
Washington, D.C. 20231

Dear Commissioner:

In response to the Official Action dated June 6, 2002, please amend this application as follows:

IN THE CLAIMS

Please cancel claim 3.

Please add claims 9-10 to read as follows:

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GROUP 1700

9. (New) A method for forming a multi-layer wiring structure, comprising the following steps:

(a) etching to form via-holes or wiring gutters through a resist mask on an insulating film between layers of a silica system having a dielectric constant being equal to or less than 3.5, said insulating film between the layers of the silica system containing carbon from 5% by atomic weight to 25% by atomic weight;

(b) filling up said wiring gutters or said via-holes with conductive material using a damascene method; and